



TC-THE Series

Shin-Etsu Silicones of America, Inc.
800-544-1745

Product Features

- Soft and compressible
- Excellent thermal conductivity
- 0.50, 1.00, 1.50, 2.00, 2.50, and 3.00mm thicknesses available
- Low stress and contact thermal resistance
- Excellent electrical insulation
- UL 94 V-0 rated

Typical Applications

- Vehicle modules
- Power supplies
- LED modules

Typical Properties

Type	Soft and Ultra Soft Thermal Pads
UL	Y
Low Molecular Weight Siloxane Stripped?	Y
Color	Light Blue/Red-Violet
Density @ 23C (g/cm ³)	2.90
Shore 00 Hardness	60
Dielectric Strength (kV/mm)	20.0
Thermal Conductivity (W/m·K)	2.50
Thermal Resistance (C/W)	0.66
Usable Temp. Range (C)	-40 to +180
Thickness (mm)	1.0
Reinforced Layer	Composite
Sheet Size (mm)	300 x 400

Note: Values are not for specification purposes.

Physical properties are typical for the thickness given. Other thicknesses may have slightly varying properties and are available upon request.

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